

# BEST AVAILABLE COPY

| L Number | Hits    | Search Text   | DB  | Time stamp       |
|----------|---------|---|---|------------------|
| 1        | 2291677 | wafer or wafers or substrate or substrate or semiconductor  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 09:39 |
| 2        | 15906   | dicing  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 09:39 |
| 3        | 7490    | vacuum near3 (chuck or chucks)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 09:39 |
| 4        | 20097   | (wafer or wafers or substrate or substrate or semiconductor) with dicing wiht (vacuum near3 (chuck or chucks))                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 09:39 |
| 5        | 61      | (wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:06 |
| 6        | 20      | "5809987"   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 09:55 |
| 7        | 0       | ((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and farnsworth.in. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:06 |
| 8        | 5       | ((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and farnsworth.in. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:09 |
| 9        | 243643  | blades  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:07 |
| 10       | 0       | ((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) same blades        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:07 |
| 11       | 22      | ((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and blades         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:07 |
| 12       | 53      | ((wafer or wafers or substrate or substrate or semiconductor) with dicing) and farnsworth.in.                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:13 |
| 13       | 402     | ((wafer or wafers or substrate or substrate or semiconductor) with dicing) and blades   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/05/08 10:14 |